

ABSTRACT

An optical data communication module 1 comprises a light emitting element 3, a light receiving element 4, and an IC chip 5. The light emitting element 3, the light receiving element 4, and the IC chip 5 are mounted on a base board 2, and are covered by a sealing resin package 6. The base board 2 is formed with a recess 22 including an inner surface covered by a metal film 7 which is grounded, and the recess 22 accommodates the light emitting element 3.